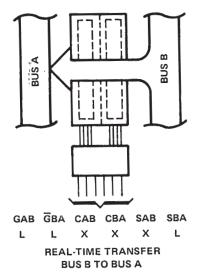
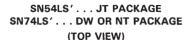
- Bus Transceivers/Registers
- Independent Registers and Enables for A and B Buses
- Multiplexed Real-Time and Stored Data
- Choice of True and Inverting Data Paths
- Choice of 3-State or Open-Collector Outputs to A Bus
- Dependable Texas Instruments Quality and Reliability

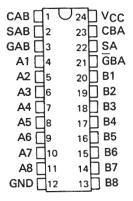
DEVICE	A OUTPUT	B OUTPUT	LOGIC
'LS651	3-State	3-State	Inverting
'LS652	3-State	3-State	True
'LS653	Open-collector	3-State	Inverting

description

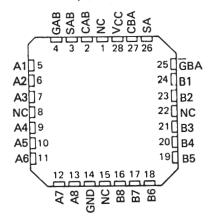
These devices consist of bus transceiver circuits, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers. Enable GAB and $\overline{G}BA$ are provided to control the transceiver functions. SAB and SBA control pins are provided to select whether realtime or stored data is transferred. A low input level selects real-time data, and a high selects stored data. The following examples demonstrate the four fundamental bus-management functions that can be performed with the 'LS651, 'LS652, and 'LS653.



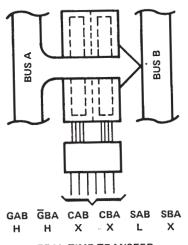




SN54LS'...FK PACKAGE (TOP VIEW)



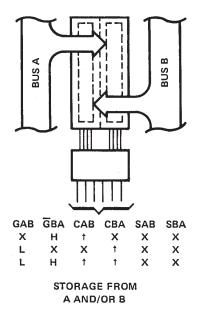
NC - No internal connection

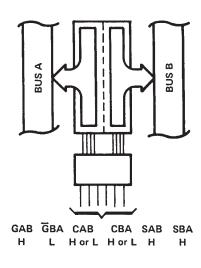


REAL-TIME TRANSFER BUS A TO BUS B



SDLS191A - JANUARY 1981 - REVISED DECEMBER 2000





TRANSFER STORED DATA TO A AND/OR B

Data on the A or B data bus, or both, can be stored in the internal D flip-flop by low-to-high transitions at the appropriate clock pins (CAB or CBA) regardless of the select or enable control pins. When SAB or SBA are in the real-time transfer mode, it is also possible to store data without using the internal D-type flip-flops by simultaneously enabling GAB and $\overline{G}BA$. In this configuration each output reinforces its input. Thus, when all other data sources to the two sets of bus lines are at high impedance, each set of bus lines will remain at its last state.

The SN54LS651 through SN54LS653 are characterized for operation over the full military temperature range of $-55\,^{\circ}$ C to 125 °C. The SN74LS651 through SN74LS653 are characterized for operation from 0 °C to 70 °C.

FUNCTION TABLE

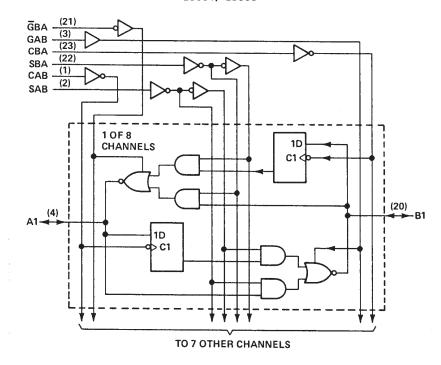
		INP	UTS			DAT	A I/O*	OPERATION OR FUNCTION				
GAB	ĞВА	CAB	CBA	SAB	SBA	A1 THRU A8 B1 THRU B8		'LS651, 'LS653	'LS652, 'LS654			
L	Н	H or L	H or L	Х	Х	1	1	Isolation	Isolation			
L	Н	†	1	Х	X	Input	Input	Store A and B Data	Store A and B Data			
X	Н	†	H or L	Х	Х	Input	Not specified	Store A, Hold B	Store A, Hold B			
Н	Н	1	†	Х	X	Input	Output	Store A in both registers	Store A in both registers			
L	Х	H or L	†	Х	Х	Not specified	Input	Hold A, Store B	Hold A, Store B			
L	L	†	†	Х	Х	Output	Input	Store B in both registers	Store B in both registers			
L	L	Х	Х	Х	L	Output	Input	Real-Time B Data to A Bus	Real-Time B Data to A Bus			
L	L	Х	H or L	Х	Н	Output	Input	Stored B Data to A Bus	Stored B Data to A Bus			
Н	Н	Х	X	L	Х	Input	Output	Real-Time A Data to B Bus	Real-Time A Data to B Bus			
Н	Н	HorL	X	Н	Х	Прис	Output	Stored A Data to B Bus	Stored A Data to B Bus			
Н.	· L	Horl	H or L	Н	н	Output	Output	Stored A Data to B Bus and	Stored A Data to B Bus and			
	-	1101 2				Output Output		Stored B Data to A Bus	Stored B Data to A Bus			

^{*} The data output functions may be enabled or disabled by various signals at the GAB and GBA inputs. Data input functions are always enabled, i.e., data at the bus pins will be stored on every low-to-high transition on the clock inputs.

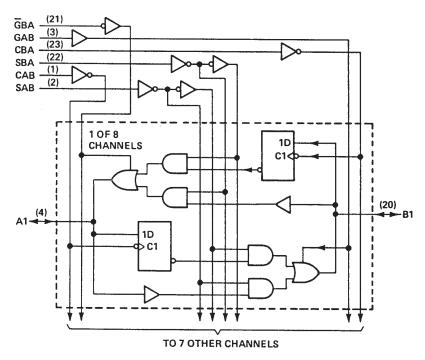


logic diagrams (positive logic)

'LS651, 'LS653



'LS652

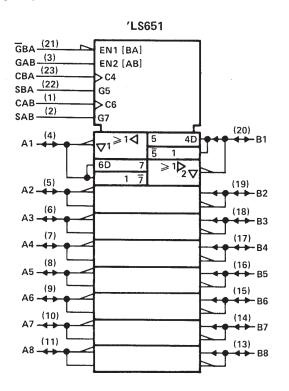


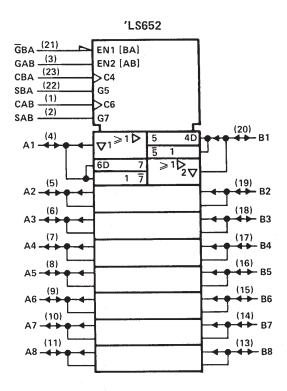
Pin numbers shown are for DW, JT or NT packages.

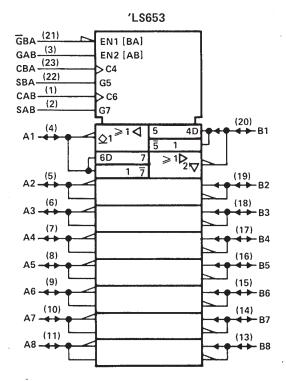


SDLS191A - JANUARY 1981 - REVISED DECEMBER 2000

logic symbols†







[†]This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for DW, JT, or NT packages.



SN54LS651, SN54LS652, SN74LS651, SN74LS652 OCTAL BUS TRANSCEIVERS AND REGISTERS

SDLS191 - JANUARY 1981 - REVISED MARCH 1988

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC	1
Input voltage: Control inputs	1
I/O ports	
Operating free-air temperature range: SN54LS651, SN54LS652 -55° C to 125°	С
SN74LS651, SN74LS652	3
Storage temperature range $\dots - 65^{\circ}C$ to 150°	С

recommended operating conditions

				N54LS6 N54LS6			N74LS6		UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	ONT
Vcc	Supply voltage		4.5	5	5,5	4.75	5	5.25	V
VIH	High-level input voltage		2	-		2			V
VIL	Low-level input voltage				0.7			0.8	V
ТОН	High-level output current				- 12			15	mA
loL	Low-level output current				12			24	mA
		CBA or CAB high	15			15			
tw	Pulse duration	CBA or CAB low	15			15			ns
		Data high or low	15			15			
t _{su}	Setup time before CAB† or CBA†	A or B	15			15			ns
th	Hold time after CAB† or CBA†	A or B	0			0			ns
TA	Operating free-air temperature		- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

P.A	ARAMETER	TEST CONDITIONS				N54LS65	52	SN74LS651 SN74LS652			UNIT
Vuc		V MIN	1 10 - 1	MIN	TYP‡		MIN	TYP‡			
VIK		V _{CC} = MIN,	I _I = - 18 mA		<u> </u>		- 1.5			- 1.5	V
		V _{CC} = MIN,	V _{IH} = 2 V,	I _{OH} = - 3 mA	2.4	3.4		2.4	3.4		1
Vон		$V_{II} = MAX,$	- 111	I _{OH} = - 12 mA	2						V
		1		l _{OH} = - 15 mA				2			
VOL		V _{CC} = MIN,	$V_{IH} = 2 V$	IOL = 12 mA		0.25	0.4		0.25	0.4	\ ,,
101		VIL = MAX,		IOL = 24 mA					0.35	0.5	\ \ \
I _f	Control inputs	V _{CC} = MAX,	V _I = 7 V				0.1			0.1	
''	A or B ports	$V_{CC} = MAX$,	V ₁ = 5.5 V				0.1			0.1	mA
ΙΉ	Control inputs	V MAY	V = 0.7.V				20			20	
'IH	A or B ports¶	VCC = MAX,	$V_1 = 2.7 \text{ V}$				20			20	μA
1	Control inputs	VMAY	V = 0.4 V				- 0.4			- 0.4	
IIL	A or B ports¶	V _{CC} = MAX,	V j = 0.4 V				- 0.4			- 0.4	mA
los§		V _{CC} = MAX,	V _O = 0 V		- 40		- 225	- 40		- 225	mA
				Outputs high		95	145		95	145	
	LS651			Outputs low		103	165		103	165	1
las		\/a== MAY		Outputs disabled		103	165		103	165	1 .
Icc		V _{CC} = MAX		Outputs high		95	145		95	145	mA
	LS652			Outputs low		103	165		103	165	1
				Outputs disabled		120	180		120	180	1

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

 $[\]P$ For I/O ports, the parameters I $_{IH}$ and I $_{IL}$ include the off-state output current.



 $^{^{\}ddagger}$ All typical values are at V_{CC} = 5 V, T_A = 25 °C. $^{\$}$ Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

SN54LS651, SN54LS652, SN74LS651, SN74LS652 OCTAL BUS TRANSCEIVERS AND REGISTERS

SDLS191 - JANUARY 1981 - REVISED MARCH 1988

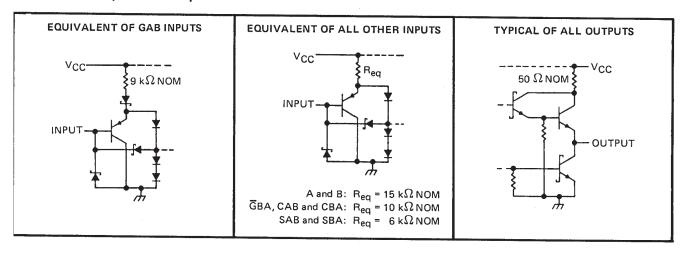
switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

PARAMETER	FROM	то	TEST COME	NITIONS		'LS651			LS652			
	(INPUT)	(OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
^t PLH	Clock	Bus				14	24		15	25	ns	
tPHL	GIOCK	bus				23	35		24	36	ns	
^t PLH	Bus	Bus				9	18		12	18	ns	
^t PHL	Dus	Bus				20	30		13	20	ns	
^t PLH	Select, with					31	.47		23	35	ns	
^t PHL	bus input high [†]	0	R _L = 667 Ω, See Note 2	CL = 45 pF,		22	33		21	32	ns	
^t PLH	Select, with	Bus				23	35		33	50	ns	
^t PHL	low†					19	30		15	23	ns	
^t PZH	Ğва	A Bus				29	44		30	45	ns	
^t PZL	GBA	A Bus				40	60		36	54	ns	
^t PZH	GAB	B Bus				19	29		20	30	ns	
^t PZL	GAB	b bus				26	40		25	38	ns	
^t PHZ	Ğва	Δ Β			1	25	. 38		25	38	ns	
^t PLZ	GBA	A Bus	$R_L = 667 \Omega$,	Cլ = 5 pF,		19	30		19	30	ns	
^t PHZ	GAB	P. P. vo	See Note 2			25	38		25	38	ns	
^t PLZ	GAB	B Bus				19	30		19	30	ns	

tpLH = propagation delay time, low-to-high-level output.

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

schematics of inputs and outputs



tpHL = propagation delay time, high-to-low-level output

tpzH = output enable time to high level

tpzL = output enable time to low level

tpHZ = output disable time from high level

tpLZ = output disable time from low level tpLZ = output disab

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC
Input voltage: All inputs and A I/O ports
B I/O ports
Operating free-air temperature range: SN54LS65355°C to 125°C
SN74LS653 0°C to 70°C
Storage temperature range65°C to 150°C

recommended operating conditions

			s	N54LS6	553	SI	N74LS6	53	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	٧
V _{IH} High-level input voltage						2			V
VIL	Low-level input voltage				0.7			8.0	V
Voн	High-level output voltage	A ports			5.5			5.5	V
Іон	High-level output current	B ports		,	- 12			- 15	mA
loL	Low-level output current				12			24	mA
		CBA or CAB high	15			15			
t _W	Pulse duration	CBA or CAB low	30			30			ns
		Data high or low	30			30			
t _{su}	Setup time	A or B	15	-		15			ns
-su	before CAB↑ or CBA↑	7, 6, 5							
t.	Hold time	A or B	0			0			ns
th	after CAB† or CBA†	7013	0						
TA	Operating free-air temperature		- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		Т	EST CONDITIO	_{NS} †	SI	N54LS6	53	s	N74LS6	553	UNIT
					MIN	TYP‡	MAX	MIN	TYP‡	MAX	
VIK		V _{CC} = MIN,	I ₁ = - 18 mA				- 1.5			- 1.5	V
		V _{CC} = MIN,	V _{IH} = 2 V,	I _{OH} = - 3 mA	2.4	3.4		2.4	3,4		
Voн	B ports	VIL = MAX		IOH = - 12 mA	2						V
				10H = - 15 mA				2			İ
ЮН	A ports	V _{CC} = MIN,	$V_{OH} = 5.5 V$				0.1			0.1	mA
Val		V _{CC} = MIN,	V _{IH} = 2 V,	IOL = 12 mA		0.25	0.4		0.25	0.4	V
VOL		VIL = MAX		IOL = 24 mA					0.35	0.5	1 *
1 ₁	Control inputs	V _{CC} = MAX,	V _I = 7 V				0.1			0.1	mA
'1	A or B ports	V _{CC} = MAX,	V ₁ = 5.5 V				0.1			0.1	1111/4
Leve	Control inputs	V _{CC} = MAX,	V ₁ = 2.7 V				20			20	μΑ
ΙΗ	A or B ports	VCC - WAX,	V - 2.7 V				20			20	μ^
IL	Control inputs	V _{CC} = MAX,	V ₁ = 0.4 V				- 0.4			- 0.4	mA
11	A or B ports¶	VCC - WAX,					- 0.4			- 0.4]
los§	B ports	V _{CC} = MAX,	V _O = 0 V		- 40		- 225	- 40		- 225	mA
				Outputs high		95	145		95	145	
	LS653			Outputs low		103	165		103	165	
Icc		V _{CC} = MAX		Outputs disabled		103	165		103	165	mA
.00		T CC - WAX		Outputs high		95	145		95	145] '''^
	LS654	_S654		Outputs low		105	170		105	170	
				Outputs disabled		120	180		120	180	

 $^{^{\}dagger}$ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. ‡ All typical values are at V_{CC} = 5 V, T_A = 25 °C.

 $[\]P$ For I/O ports, the parameters $I_{\mbox{\scriptsize IH}}$ and $I_{\mbox{\scriptsize IL}}$ include the off-state output current.



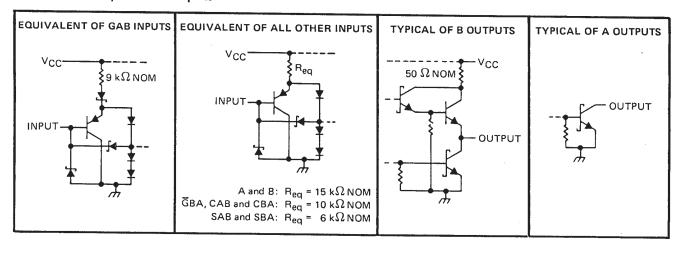
Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

switching characteristics, V_{CC} = 5 V, T_A = 25 °C

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
^t PLH	СВА	A D			25	38	
tPHL	СВА	A Bus			26	39	ns
tPLH	САВ	B Bus	- -		15	23	
tpHL	CAB	B bus			24	36	ns
^t PLH	A Bus	B Bus	1		10	18	
t _{PHL}	// Dus	D Dus			20	30	กร
^t PLH	B Bus	A Bus			21	32	
^t PHL	5 543	A Dus			16	24	ns
^t PLH	SBA†	A D	$R_L = 667 \Omega$, $C_L = 45 pF$,		38	57	
^t PHL	(with B high)	A Bus	See Note 2		26	39	ns
tplH	SBA [†]		1		34	51	
^t PHL	(with B low)	A Bus			23	35	ns
^t PLH	SAB [†]		1		32	48	
t _{PHL}	(with A high)	B Bus			22	33	ns
tPLH	SAB [†]		-				
tPHL	(with A low)	B Bus			24	36 30	ns
tPLH			1		23	35	
tPHL	Ğва	A Bus			37	55	ns
^t PZH	0.15				19	29	
tPZL	GAB	B Bus	$R_L = 667 \Omega$, $C_L = 5 pF$,		25	38	ns
^t PHZ	CAR	5.5	See Note 2		26	39	
tPLZ	GAB	B Bus			19	29	ns

[†]These parameters are measured with the internal output state of the storage register opposite to that of the bus input. NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

schematics of inputs and outputs









PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LS651DW	OBSOLETE	SOIC	DW	24		TBD	Call TI	Call TI
SN74LS651DWR	OBSOLETE	SOIC	DW	24		TBD	Call TI	Call TI
SN74LS651NT	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI
SN74LS652DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS652DWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS652DWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS652DWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS652DWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS652DWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS652NT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS652NTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

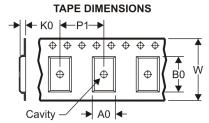
Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS652DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS652DWR	SOIC	DW	24	2000	346.0	346.0	41.0

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products Amplifiers amplifier.ti.com Data Converters dataconverter.ti.com DSP dsp.ti.com Clocks and Timers www.ti.com/clocks Interface interface.ti.com Logic logic.ti.com Power Mgmt power.ti.com Microcontrollers microcontroller.ti.com www.ti-rfid.com RF/IF and ZigBee® Solutions www.ti.com/lprf

Applications	
Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Medical	www.ti.com/medical
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2008, Texas Instruments Incorporated